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TITLE: Apparatus and method for removing surface molding resin of packaged semiconductor or electronic component

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BASIC-ABSTRACT:

NOVELTY - An apparatus and a method for removing surface molding resin of a packaged semiconductor or an electronic component are provided to remove the surface molding resin by using a mechanical milling method or a chemical wet etch method.

DETAILED DESCRIPTION - A supporter(10) is used for supporting a sample. A CCD(Charge Coupled Device) camera(30) is used for photographing a shape of the sample. An X, a Y, and a Z-axis stage(41,42,43) are used for shifting or fixing the sample to a desired position. A chemical discharge tube is used for supplying an etching solution in order to remove chemically molding resin. An etching solution injection tube is adhered on an end portion of the chemical discharge tube. The etching solution injection tube is used for performing a wet etch process by using the etching solution. An etching solution heating portion(70) heats the etching solution to a predetermined temperature. A cleaning portion performs a cleaning process for the sample.

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS: APPARATUS METHOD REMOVE SURFACE MOULD RESIN PACKAGE SEMICONDUCTOR ELECTRONIC COMPONENT

DERWENT-CLASS: A32 A85 L03 U11

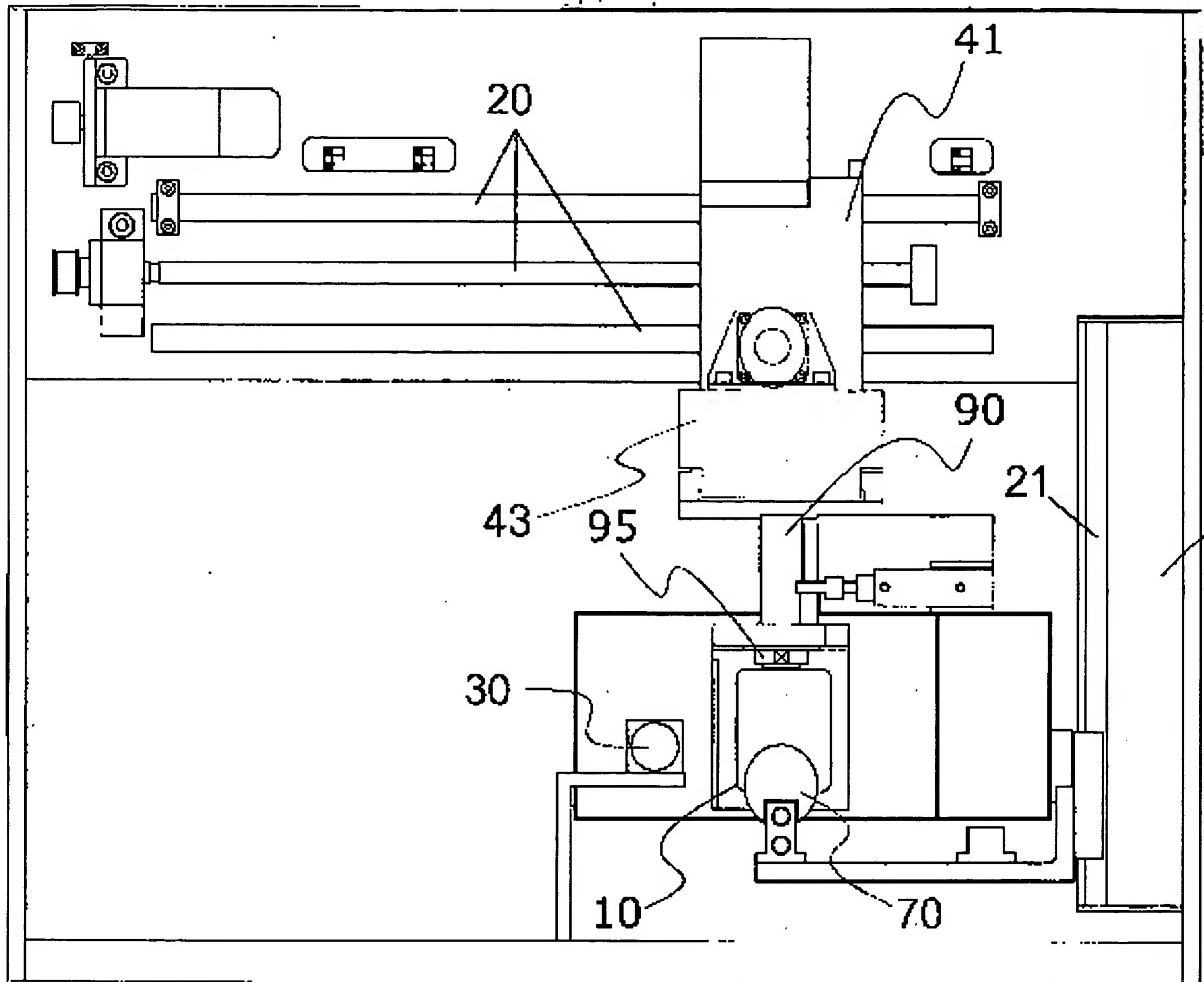
CPI-CODES: A11-A05; A11-C04D; A12-E01; A12-E07C; L04-C07C; L04-D;

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A ← → B



x

A ← → B

y